

K900G6

2U4N8P Intel® Xeon® Scalable Processor-based System

Highlights

- Best Virtualization Solution with Optimal TCO and Enhanced Security
- Scalability Unleashed by Latest Technologies such as DDR5, PCIe Gen5 and OCP 3.0
- Excellent Serviceability and Flexibility Brought by Modular Design







Virtualization Hyperconverged Storage

e Computing

Cloud

High End Enterprise Server





K900G6 is powered by a 4th. Generation Intel Eagle stream with Intel Emmitsburg chipset and Intel Sapphire Rapids dual Intel socket (LGA 4677) series is optimized for supporting high processor TDPs for its class. It is designed with two memory controllers that support 8 channels DDR5 per processor (up to 4800MTS @ 1DPC). The memory capacity is up to 4TB DDR5 at 16 channels when populated with 256GB of DDR5 DIMM modules. It is equipped with high speed PCIe Gen5 interconnect linking the processor I/O and subsystems with bandwidth, gigatransfer and frequency that doubled compared to prior generations. The improved performance and power efficiency makes it ideal for high performance computing (HPC) cloud native and big data applications.

Reliability Accessibility Serviceability (RAS)

K900G6 processor is equipped with extensive enterprise server-class RAS capabilities. Memory data is protected with advanced ECC in addition to the standard DDR5 RAS features. To enhanced availability, the system provides highly modular design, supporting tool-less operations of serviceable parts, as well as redundancy for both power and cooling fans. Additionally, it provides increased computing density, energy efficiency and security features designed for modern or future workloads.



K900G6 Intel® Xeon® Server

Positioning	High Density Compute
Form Factor	2U4N8P W x H x D: 448x 875x 916 mm (17.63x 3.44x 38.43 inch)
Processor	Sapphire Rapids + HBM (optional) (2CPUs) Intel [®] Socket (LGA 4677)Up to 350W TDP UPI up to 16GT/s
Memory Slot	8 Channels DDR5 per CPU @ 4800MTS (1DPC) (Total: 16 DIMMs)
PCIe Lanes	PCIe Gen5 80 lanes per processor
Expansion Slot	1 x PCle Gen5 x16 GenZ slot 1 x PCle Gen5 x16 MClO slot 1 x PCle Gen5 x4 GenZ slot
System I/O	Rear (Per node) • 1 x USB3.0 port • VGA output port • 1xPower button with LED • 1 x UID button with LED • 1 x RJ45 management port • 1 x RJ45 1G port • 1 x Health LED
Network Controller	Intel I210 1Gb single port OCP 3.0 Connector
Storage Controller	Support up to 2 x U.2 NVMe SSDs per Node Support M.2 22110 Front(2U 4Node) • Support 2 x 4SFF U.2 NVMe HDD Bays
System Management	Aspeed AST2600 BMC • 8GB DDR4 • Support 1 management LAN port • VGA
ТРМ	Embedded TPM2.0
VGA	VGA Video integrated into BMC
Thermal Sensor	TMP468 TMP75
Power Supply	Four 2400W PSUs/3+1
Fan	Four 4056 Fans per node



About Inventec Data Center Solutions (Inventec EBG)

Inventec Data Center Solutions (Inventec EBG) was established in 1998 and has been focusing on the design and manufacturing of server systems in Inventec Corporation. Over decades, Inventec EBG has been the key server system supplier of the global branding clients.

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